

Elite Advanced Laser scales up capacity with AIX G5+ C

AIXTRON Planetary® technology continues to replace Si by GaN in the manufacturing of high-performance power electronics

Herzogenrath/Germany, October 05, 2017 – AIXTRON SE (FSE: AIXA), a worldwide leading provider of deposition equipment to the semiconductor industry, announced today that Elite Advanced Laser Corporation (eLASER), a leading provider of electronics manufacturing services (EMS) for advanced optoelectronic and radio frequency (RF) components from Taiwan, has placed a repeat order for an AIX G5+ C system to produce gallium nitride (GaN) epitaxial wafers and devices for power electronics applications.

The production tool will be installed during the second half of 2017 to complement the customer's existing capacity. It integrates the Penta-Injector technology for best material uniformities across the entire wafer diameter and is equipped with a Cassette-to-Cassette (C2C) Wafer Transfer Module for full automation of GaN processes.

"We have been impressed by the speed at which eLASER has transferred their device manufacturing processes on our system technology. Therefore, we are convinced that the recent addition of our AIX G5+ C platform which has become the tool of record at leading GaN power electronics manufacturers, will support the company's goal to gain further market share in the GaN power electronics ecosystem. While offering configurations of 8x150 mm and 5x200 mm, the tool meets the toughest requirements from the silicon industry in terms of uniformity and particles. Thereby, AIXTRON's G5+ C system technology is breaking down the barriers to bring GaN into silicon production lines", says AIXTRON SE President Dr. Bernd Schulte.

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PRESS RELEASE



About AIXTRON

AIXTRON SE is a leading provider of deposition equipment to the semiconductor industry. The Company was founded in 1983 and is headquartered in Herzogenrath (near Aachen), Germany, with subsidiaries and sales offices in Asia, United States and in Europe. AIXTRON's technology solutions are used by a diverse range of customers worldwide to build advanced components for electronic and opto-electronic applications based on compound, silicon, or organic semiconductor materials. Such components are used in a broad range of innovative applications, technologies and industries. These include LED applications, display technologies, data storage, data transmission, energy management and conversion, communication, signaling and lighting as well as a range of other leading-edge technologies.

Our registered trademarks: AIXACT®, AIXTRON®, Atomic Level SolutionS®, Close Coupled Showerhead®, CRIUS®, Gas Foil Rotation®, OVPD®, Planetary Reactor®, PVPD®, TriJet®

For further information on AIXTRON (FSE: AIXA, ISIN DE000A0WMPJ6) please visit our website at: www.aixtron.com.

About eLASER

Elite Advanced Laser Corporation (eLASER) was founded in 2000 and is headquartered in Chung Ho Dist, New Taipei City, Taiwan. The company is an EMS (Electronic Manufacturing Service) service of advanced optoelectronic and RF components for information, optical and RF communication.

Additional information can be found at www.elaser.com.tw.

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